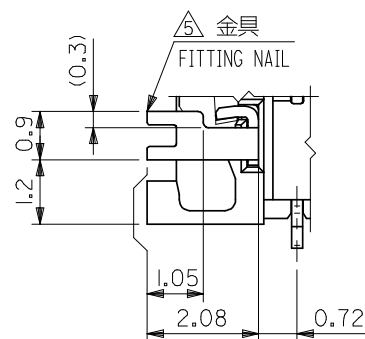
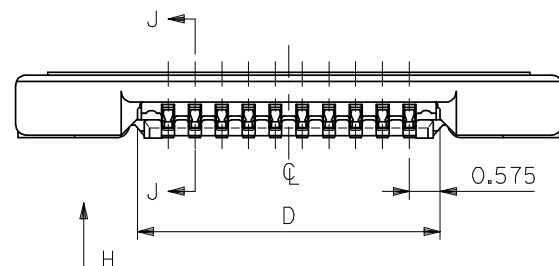
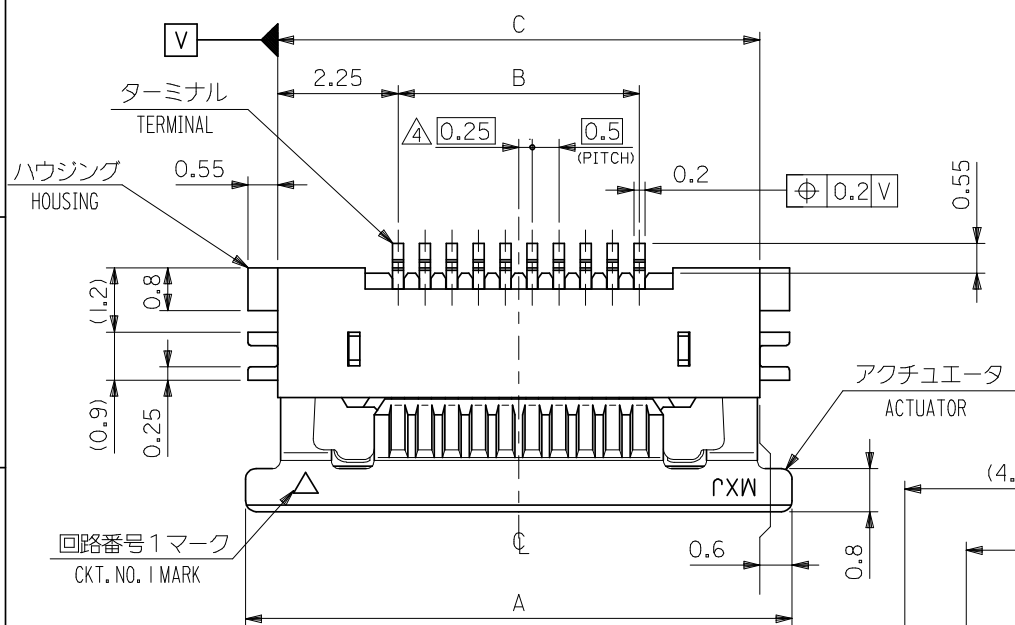
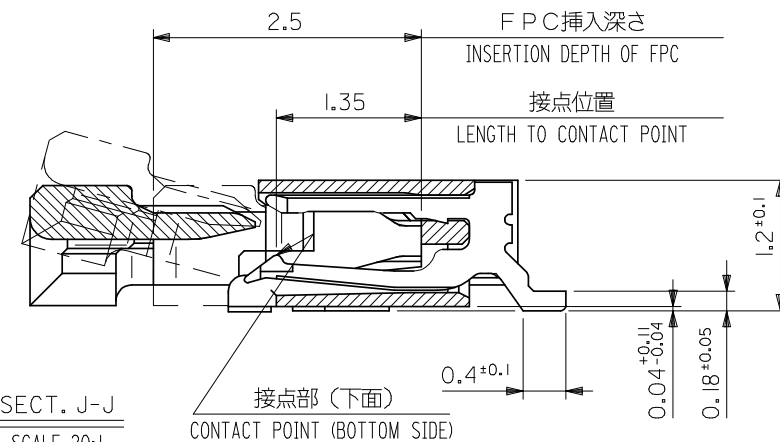




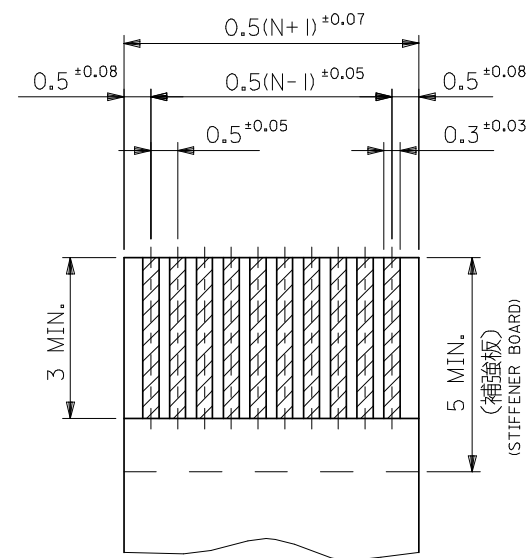
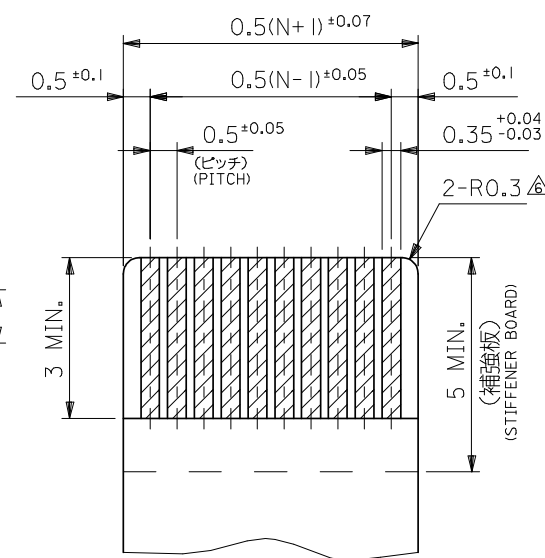
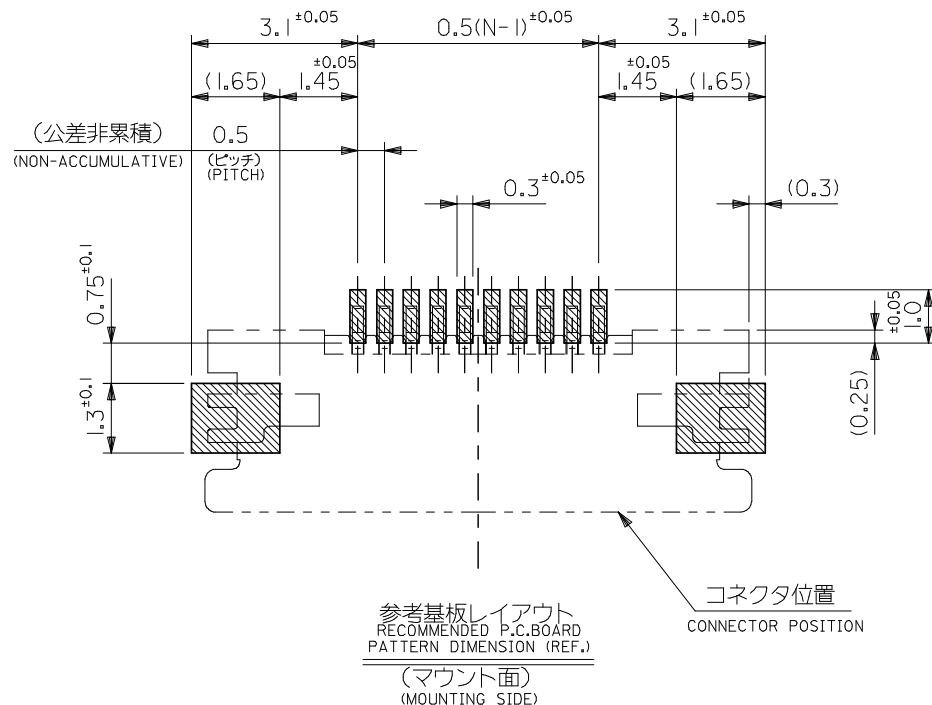
VIEW H



SECT. J-J
SCALE 20:1

D) i) D)	0.28 ±0.03	13.65	17	12.5	18.2	54548-2670	54548-26 19	26
	0.3 ±0.03	12.65	16	11.5	17.2	54548-2470	54548-24 19	24
		11.65	15	10.5	16.2	54548-2270	54548-22 19	22
		11.15	14.5	10	15.7	54548-2170	54548-21 19	21
		10.65	14	9.5	15.2	54548-2070	54548-20 19	20
		10.15	13.5	9	14.7	54548-1970	54548-19 19	19
		9.65	13	8.5	14.2	54548-1870	54548-18 19	18
		9.15	12.5	8	13.7	54548-1770	54548-17 19	17
		8.65	12	7.5	13.2	54548-1670	54548-16 19	16
		8.15	11.5	7	12.7	54548-1570	54548-15 19	15
		7.65	11	6.5	12.2	54548-1470	54548-14 19	14
		7.15	10.5	6	11.7	54548-1370	54548-13 19	13
		6.65	10	5.5	11.2	54548-1270	54548-12 19	12
		6.15	9.5	5	10.7	54548-1170	54548-11 19	11
		5.65	9	4.5	10.2	54548-1070	54548-10 19	10
		5.15	8.5	4	9.7	54548-0970	54548-09 19	9
		4.65	8	3.5	9.2	54548-0870	54548-08 19	8
		4.15	7.5	3	8.7	54548-0770	54548-07 19	7
		3.65	7	2.5	8.2	54548-0670	54548-06 19	6
		3.15	6.5	2	7.7	54548-0570	54548-05 19	5
2.65	6.0	1.5	7.2	54548-0470	54548-04 19	4		
THICKNESS OF FPC	D	C	B	A	EMBOSSD TAPE	製品番号	極数	
					ORDER No. オオーダー番号	MATERIAL No.	CIRCUIT	

REVISED	EC NO: J2008-4048	DRWN:MNABEI CHKD:THARYAMA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
				10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/01/09				
				30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX INCORPORATED			
				ANGULAR ±3 °	MATERIAL NO.		DOCUMENT NO.				
REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		SD-54548-037		1 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
（仕上がり厚さ：表参照）
（THICKNESS:SEE CHART）

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

注記 NOTES

1. 使用材料 MATERIAL

ハウジング : LCP, UL94V-0
HOUSING

アクチュエータ : PPS, UL94V-0
ACTUATOR

ターミナル :リン青銅 (t=0.2)、ニッケル下地 錫ビスマスマツキ
 TERMINAL PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING.

金具 : リン青銅 (t=0.2)、ニッケル下地 錫メッキ
FITTING NAIL PHOSPHOR BRONZE, PURE-TIN OVER NICKEL PLATING.

2. エンボステーブ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54548-**19 SHOULD BE LOCKED.

△3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 0MAX.、下方向 0.15MAX. とし、相互のバラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1MAX.

△ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.

△6 R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

7. N: 極数 N: CIRCUIT.

REVISED	EC NO.: J2008-4048	DRAWN: MNABE I 2008/06/13	CHKD: THARYAMA 2008/06/16	APPR: NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
						10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
						10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/01/09				
						30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX MOLEX INCORPORATED			
						ANGULAR ±3 °		MATERIAL NO.					
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54548-037		2 OF 2	
REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												

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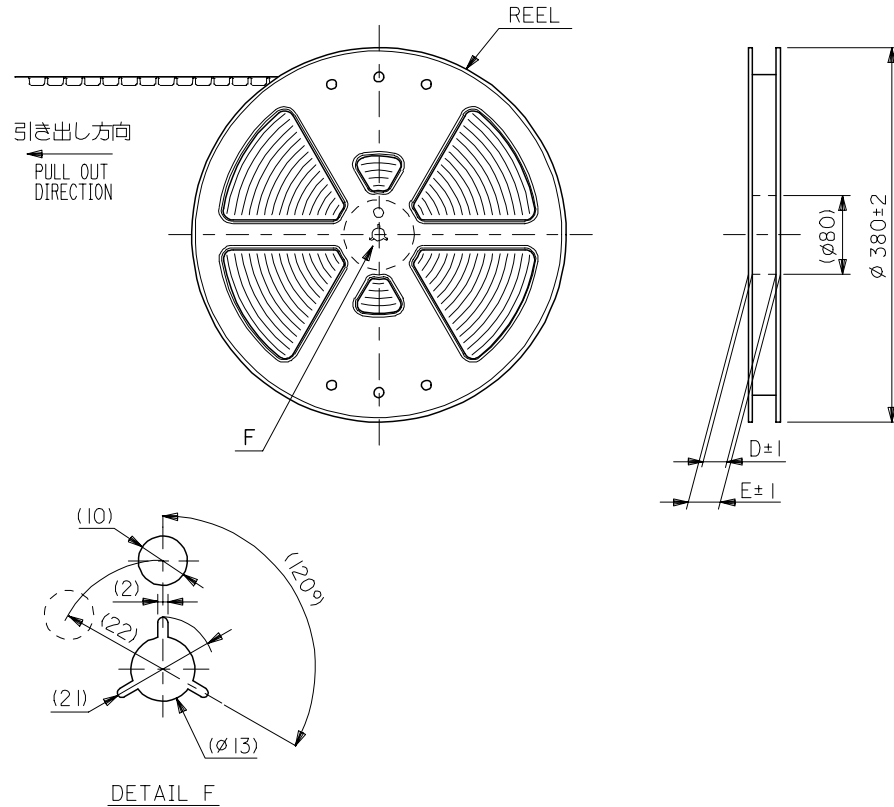
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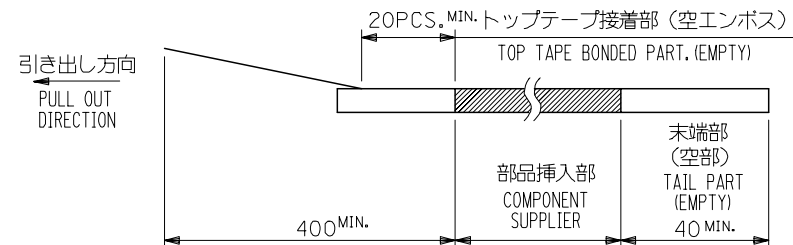
B

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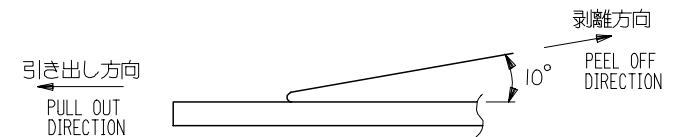


NOTES

- 製品詳細寸法については図面 SD-54548-037 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-037.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ～ 1.3N { 10gf ～ 130gf }
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N(10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET , PE , PEF
リール(REEL)：ポリスチレン (P S) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は54548-**-90の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-90.

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EN-02JA(021)

REVISED	EC NO: J2005-2516 DRAWN:MABEI CHKD:KTOYODA APPR:NUKITA	2005/02/28 2005/02/28 2005/03/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-		
				10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09			
				30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09			
				ANGULAR ±3 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54548-038	SHEET NO. 1 OF 4	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				REV						

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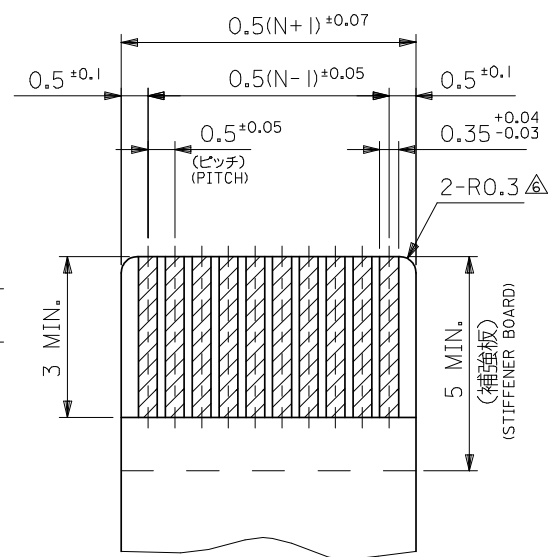
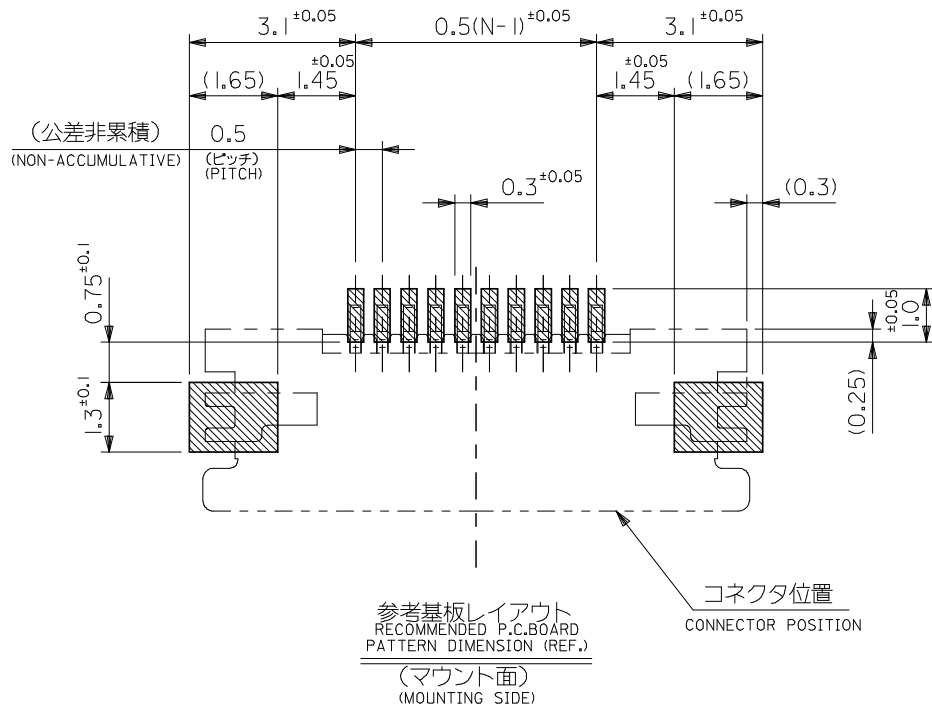
E

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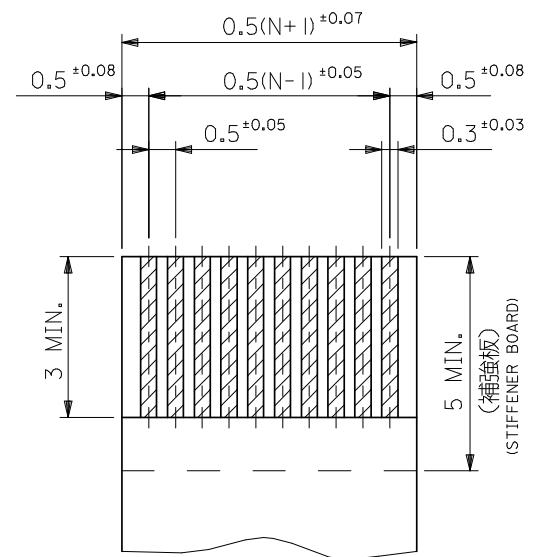
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適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)

注記 NOTES

I. 使用材料 MATERIAL

- ハウジング : LCP, UL94V-0
HOUSING
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル : リン青銅 (t=0.2)
TERMINAL PHOSPOR BRONZE
- メッキ : 接点部: 金メッキ
PLATING CONTACT PORTION : GOLD PLATING
- テール部: 鍍メッキ
SOLDERING PORTION : TIN OVER PLATING
- 下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING
- 金具 : リン青銅、鍍メッキ (t=0.2)
FITTING NAIL PHOSPOR BRONZE, TIN PLATING
- 下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING

- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
- △ R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は54548-**-21の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

2. エンボステープ極包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 54548-**-29 SHOULD BE LOCKED.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z
に対し上方向 0 MAX.、下方向 0.15 MAX.とし
相互のバツキ量は0.1 MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

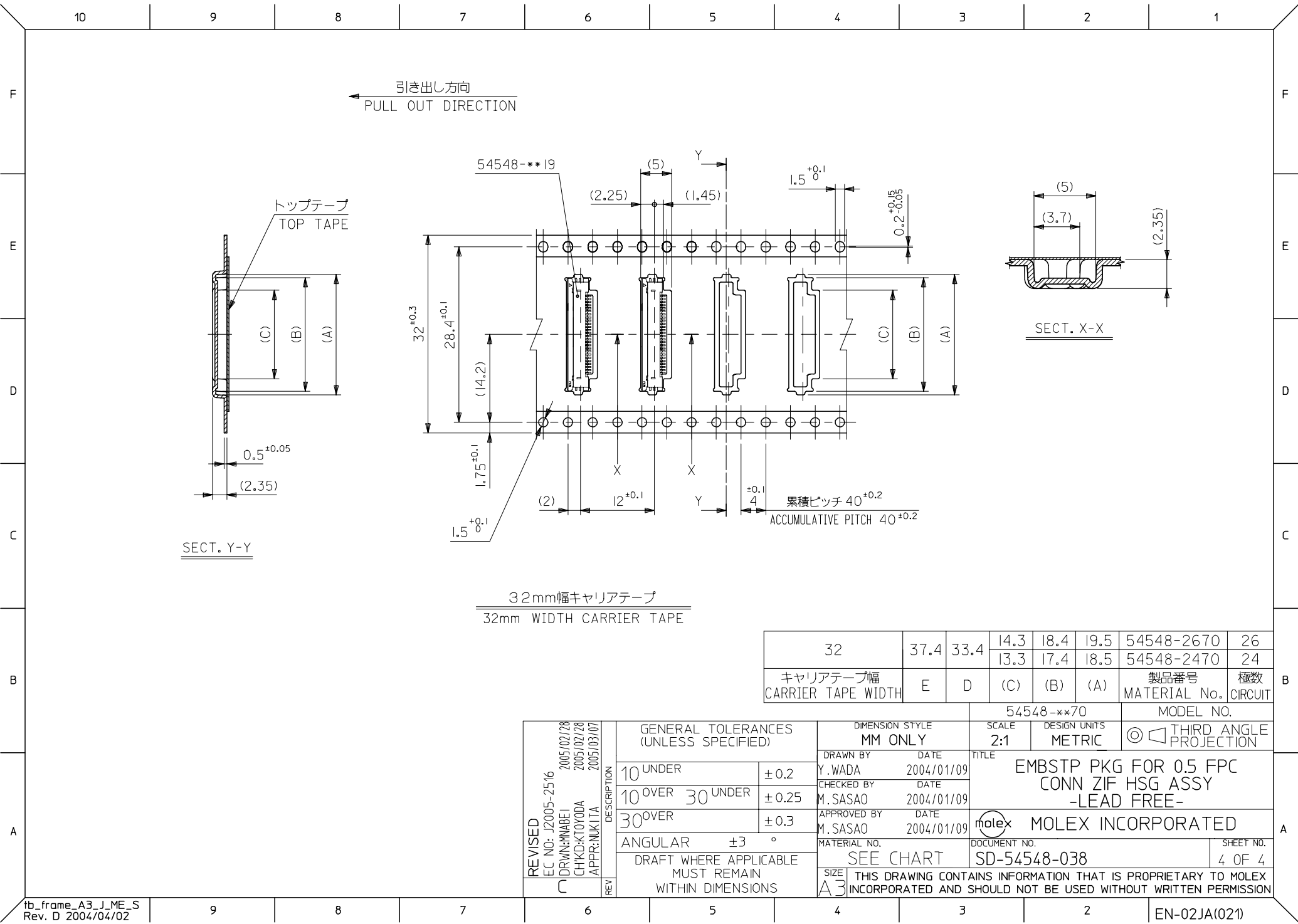
FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT
AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA		DESCRIPTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
				10 UNDER ±0.2		DRAWN BY HSHIMABUKURO DATE '04/02/10		TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-					
				10 OVER 30 UNDER ±0.25		CHECKED BY KTOJO DATE '04/02/10							
				30 OVER ±0.3		APPROVED BY MSASAO DATE '04/02/10		MOLEX MOLEX INCORPORATED					
				ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO. SD-54548-039					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SHEET NO. 2 OF 2					
				REV		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



32	37.4	33.4	14.3	18.4	19.5	54548-2670	26
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	13.3	17.4	18.5	54548-2470	24
						製品番号 MATERIAL No.	極数 CIRCUIT
						54548-**70	MODEL NO.

REVISED EC NO: J2005-2516 DRWN: MABEI CHKD: KTOYODA APPR: NUKITA	2005/02/28 2005/02/28 2005/03/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-				
			10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09					
			30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX INCORPORATED				
			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-038		4 OF 4		
			REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					